



Verification of Chiplet-based designs: Challenges and Solutions

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About me and Why I am here?

- I have deep expertise on verification of peripheral interconnects using Pure simulation and Emulation. Includes several broad market and turnkey projects from Unit Level to a complete System level testbench verification

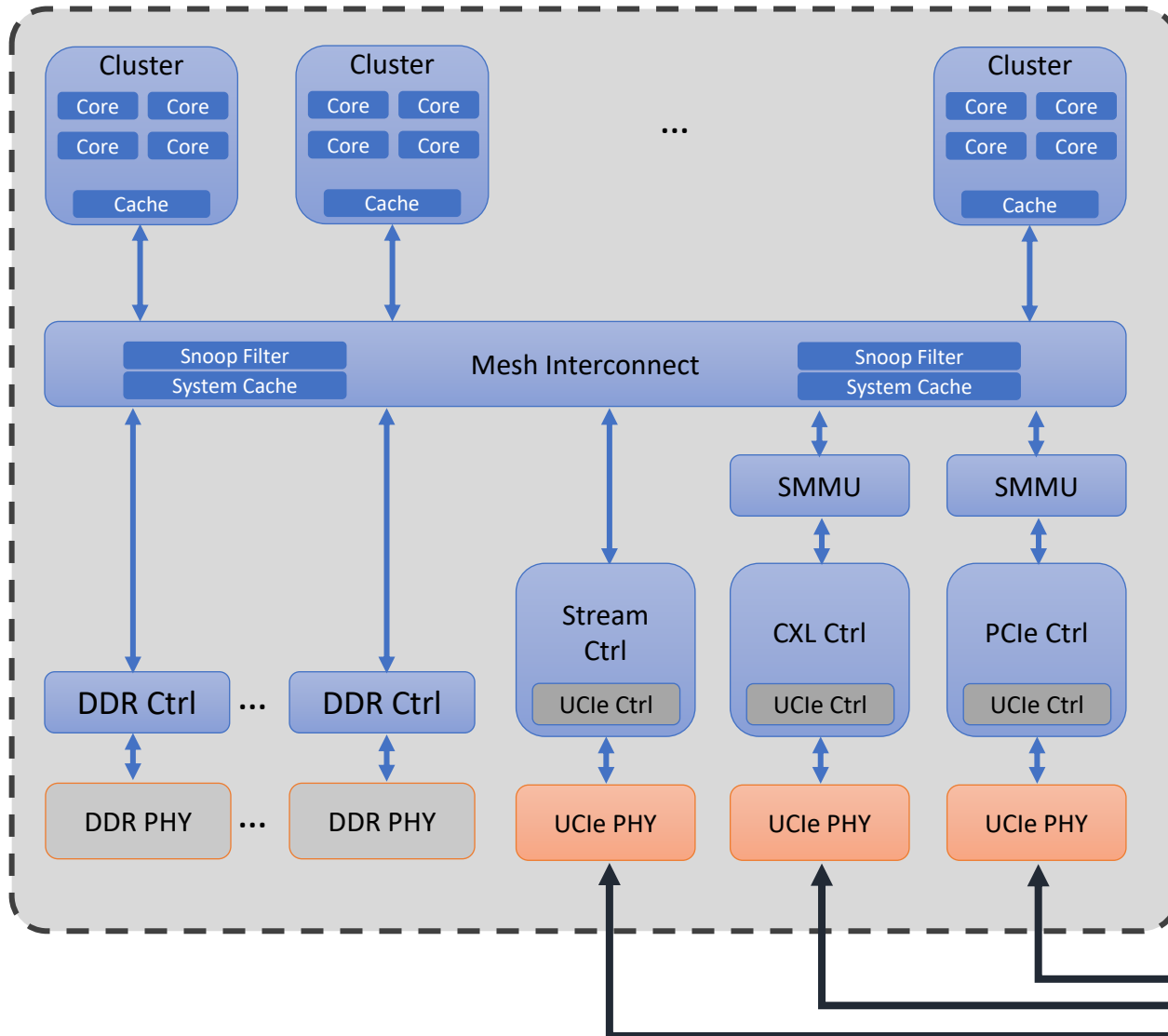
At Cadence, I am responsible for defining models and methodologies for UCle Verification by working with internal and external stakeholders

What to expect in this talk?

Leverage a simplified Dual Die Design as an Example and discuss state of the art techniques to address

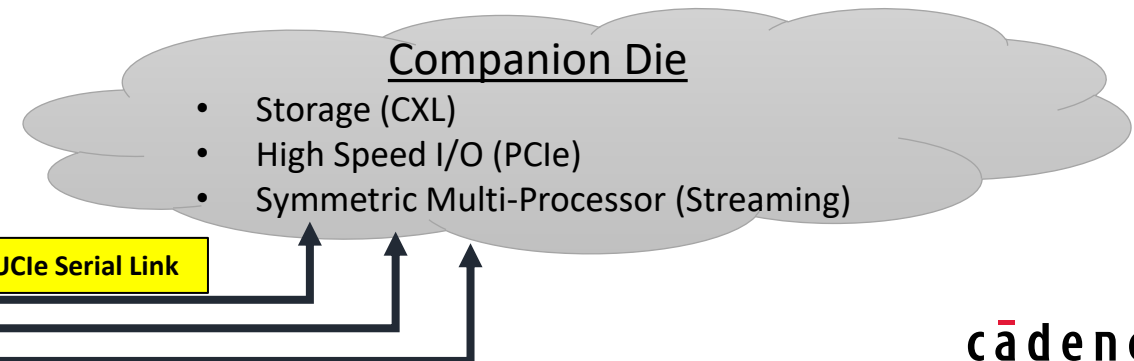
- Individual Die Verification challenges
- System Level Coherency and Traffic Latency Analysis

UCle in Action -Example Chiplet Design

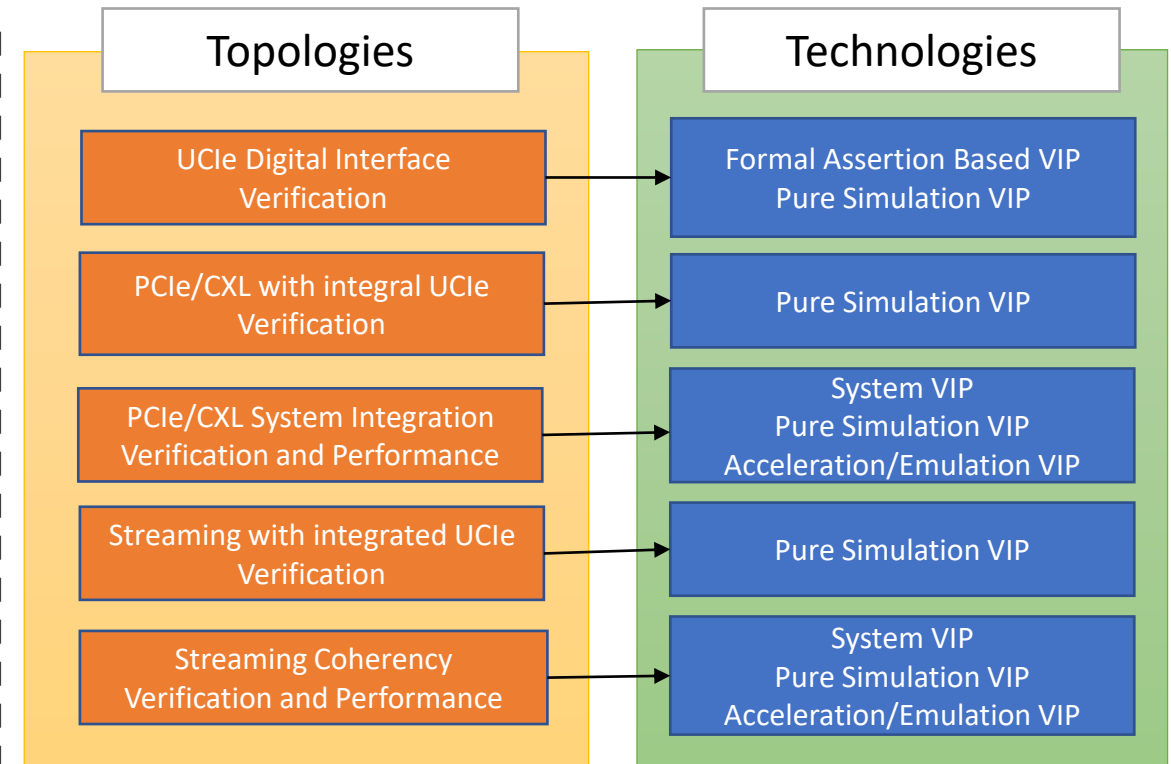
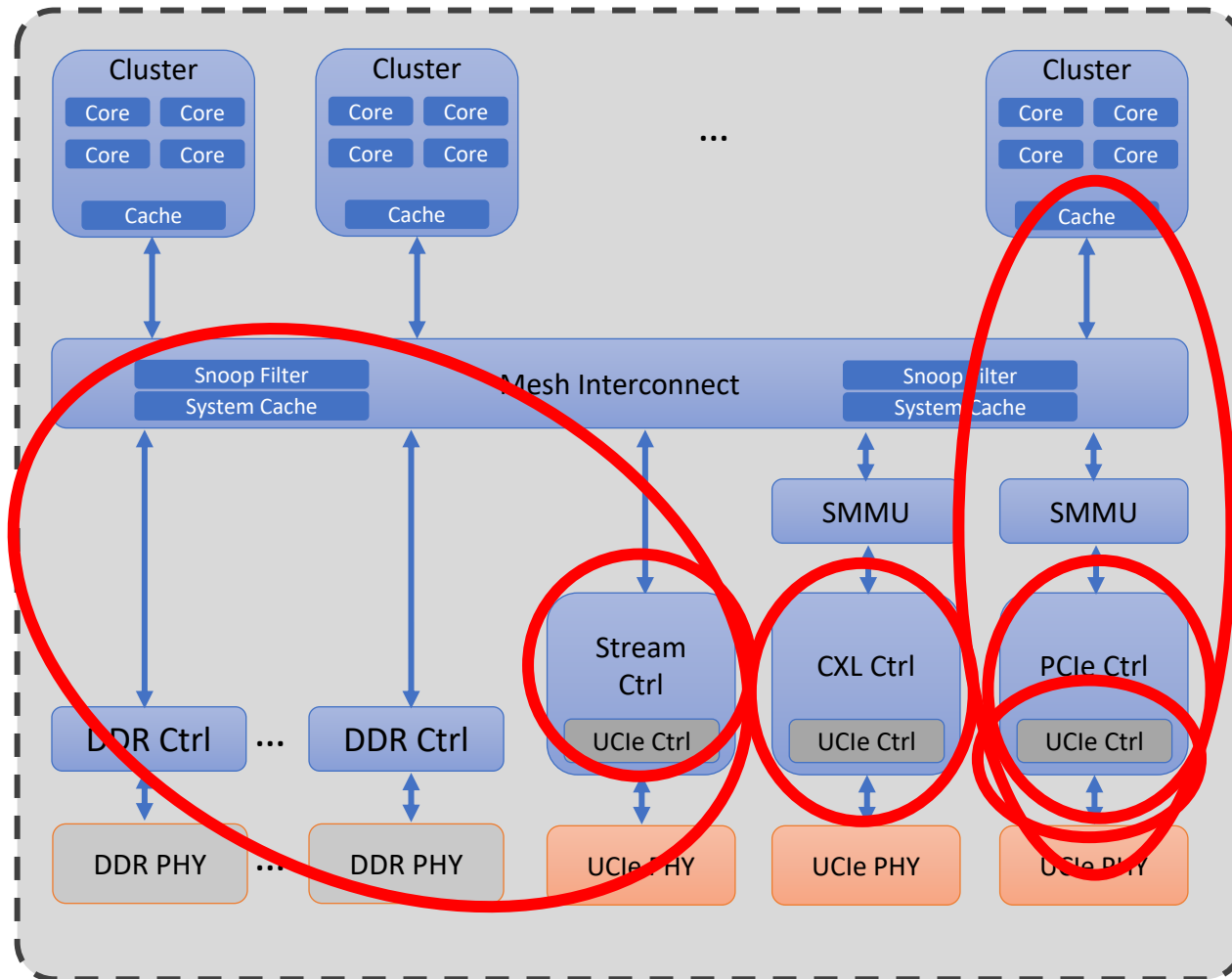


- Explosion of Design Topologies
 - Several Unit Levels in different combinations
- Multiprotocol Verification
 - PCI Express using UCle as the Transport Layer
 - CXL using UCle as the Transport Layer
 - Streaming interface
- System Level Implications
 - End-to-end Data Integrity
 - Latency Calculation or Turn Around Time (TAT)

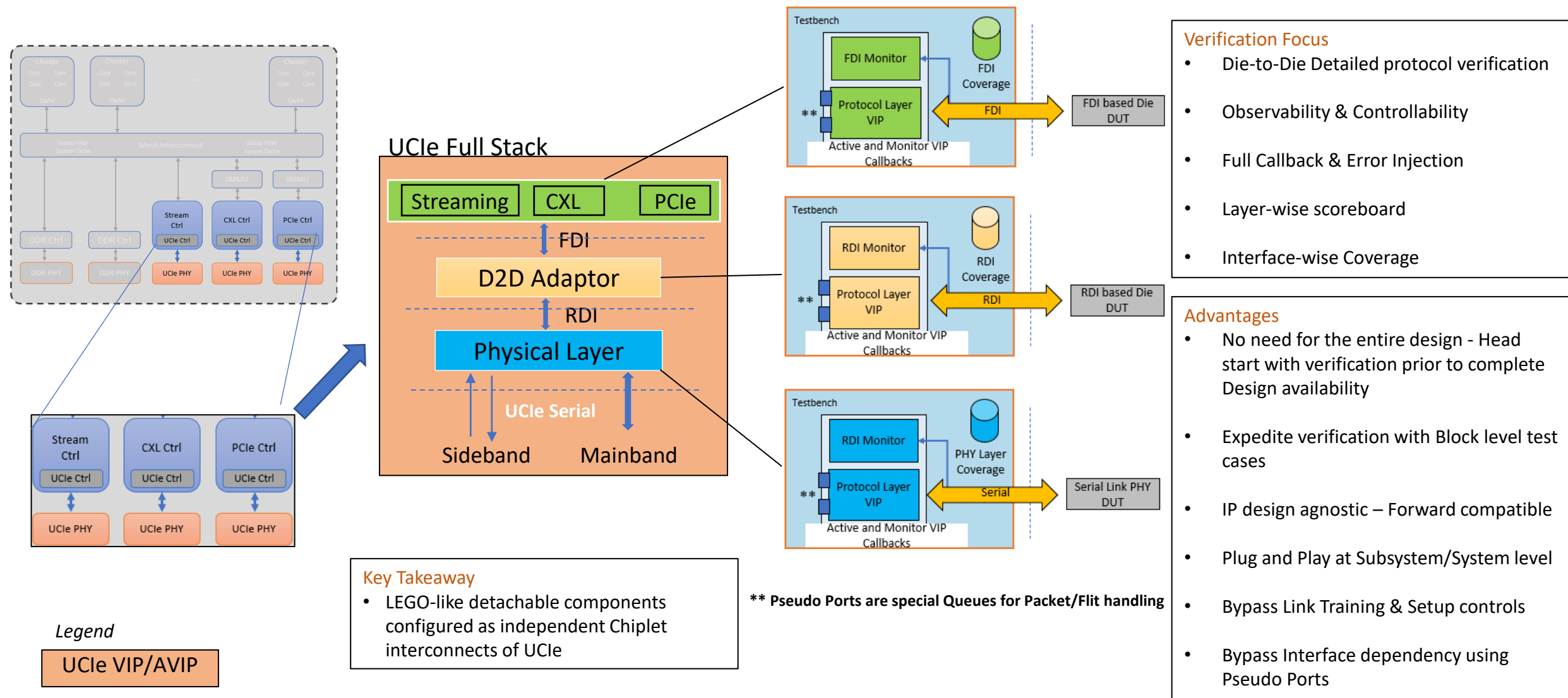
and more...



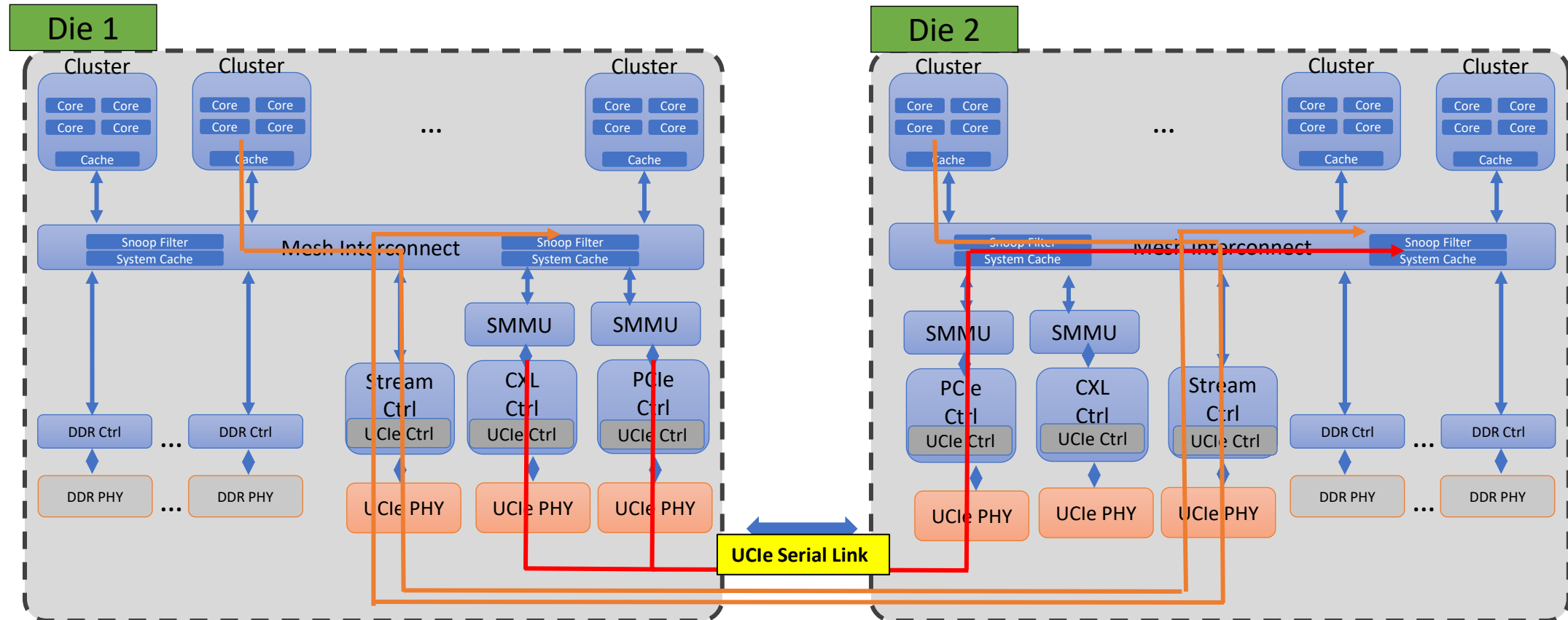
Verification Areas – Leverage Multiple Technologies



Solution - Die Disaggregated Verification

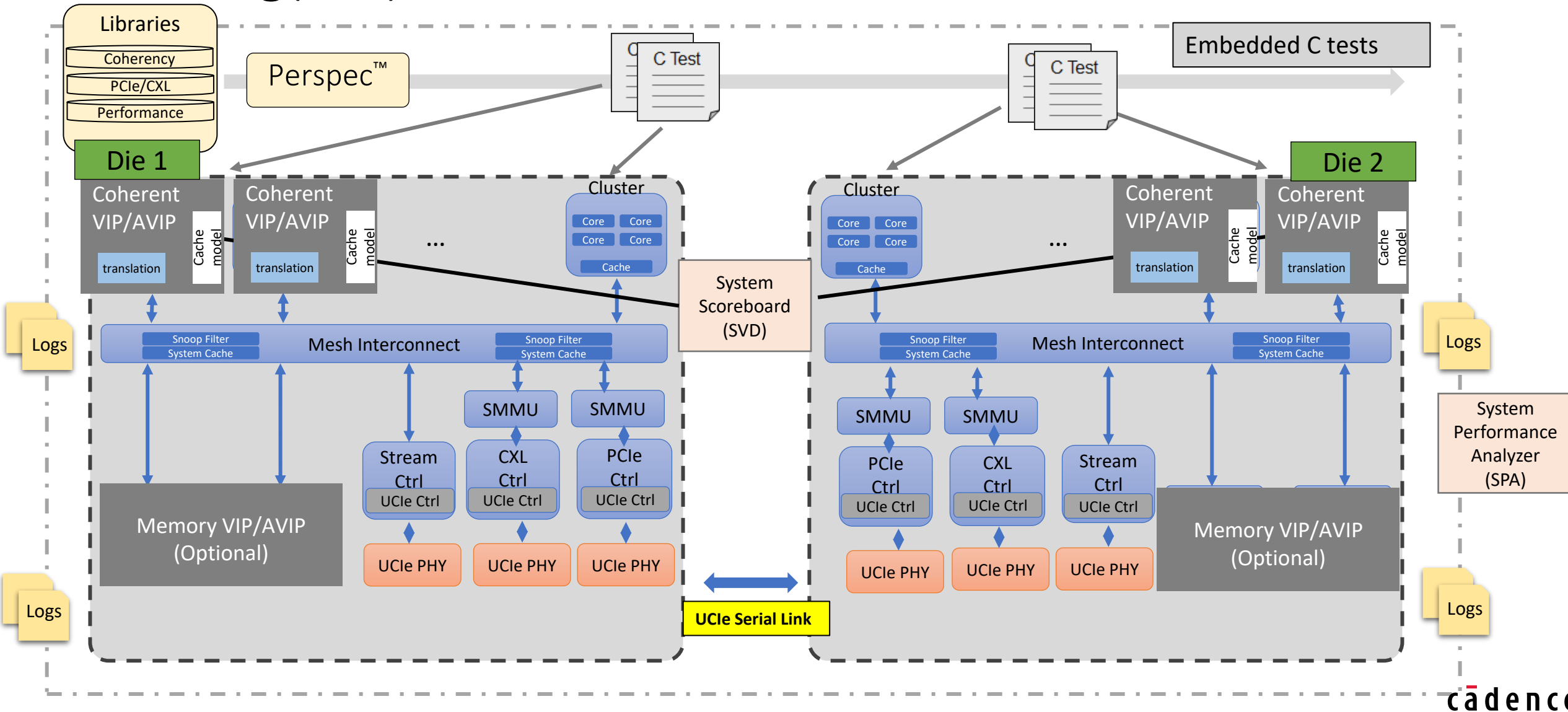


System Level- Performance Concerns

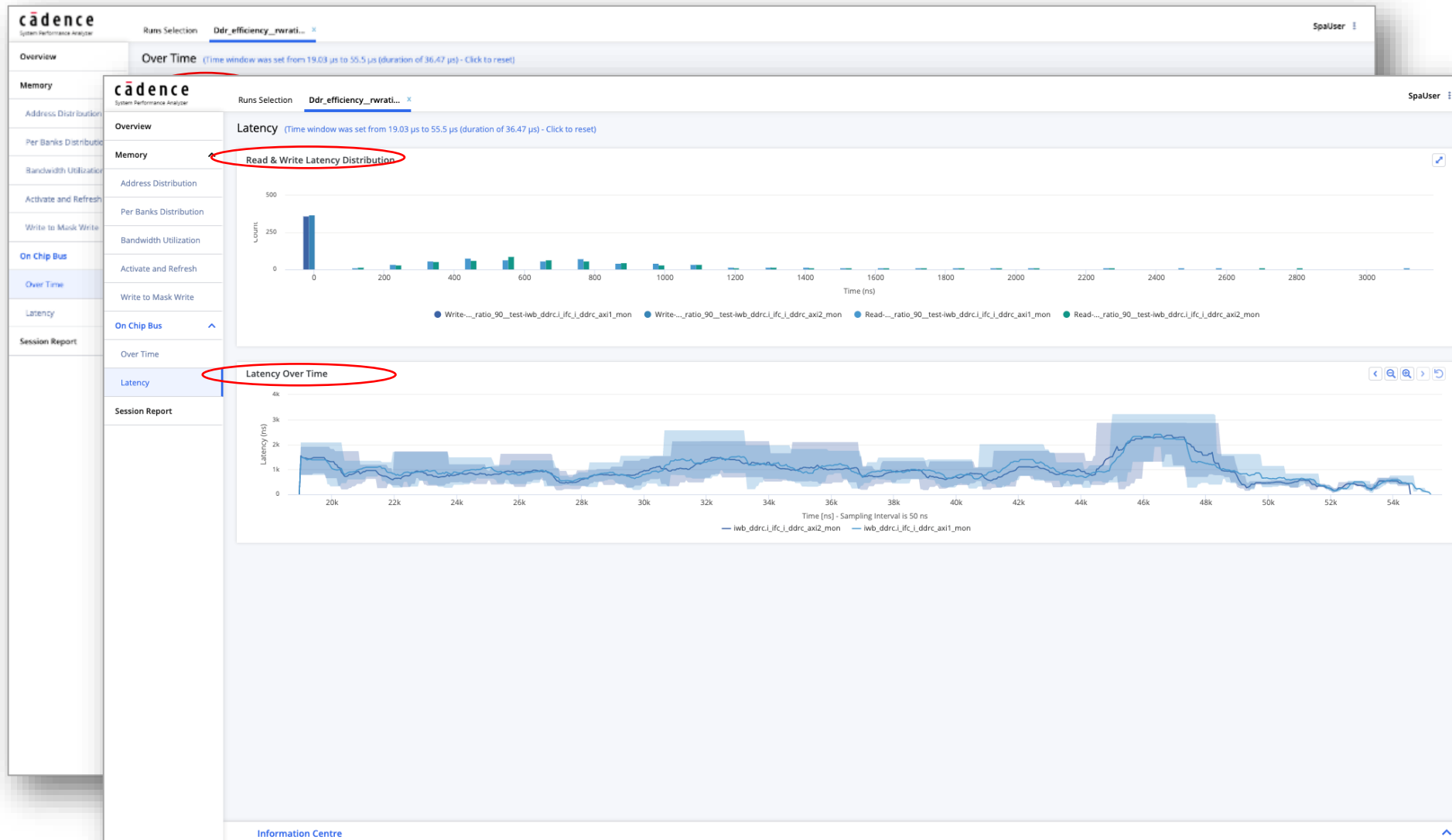


- Many steps in path from initiator to target, there are many potential "throttle" points
- Understanding and debugging bandwidth throttling requires visualization of "throttle" proxies
 - Outstanding Transaction (OT) count is the standard measure
- Localization of cache lines can have a huge impact on latency and reduce die-to-die traffic (which itself can be a throttle)
- Data packet assembly and decomposition across the Chiplet Interconnects can add significant overhead

Solution- Complete System Performance & Integrity Checking(1/2)



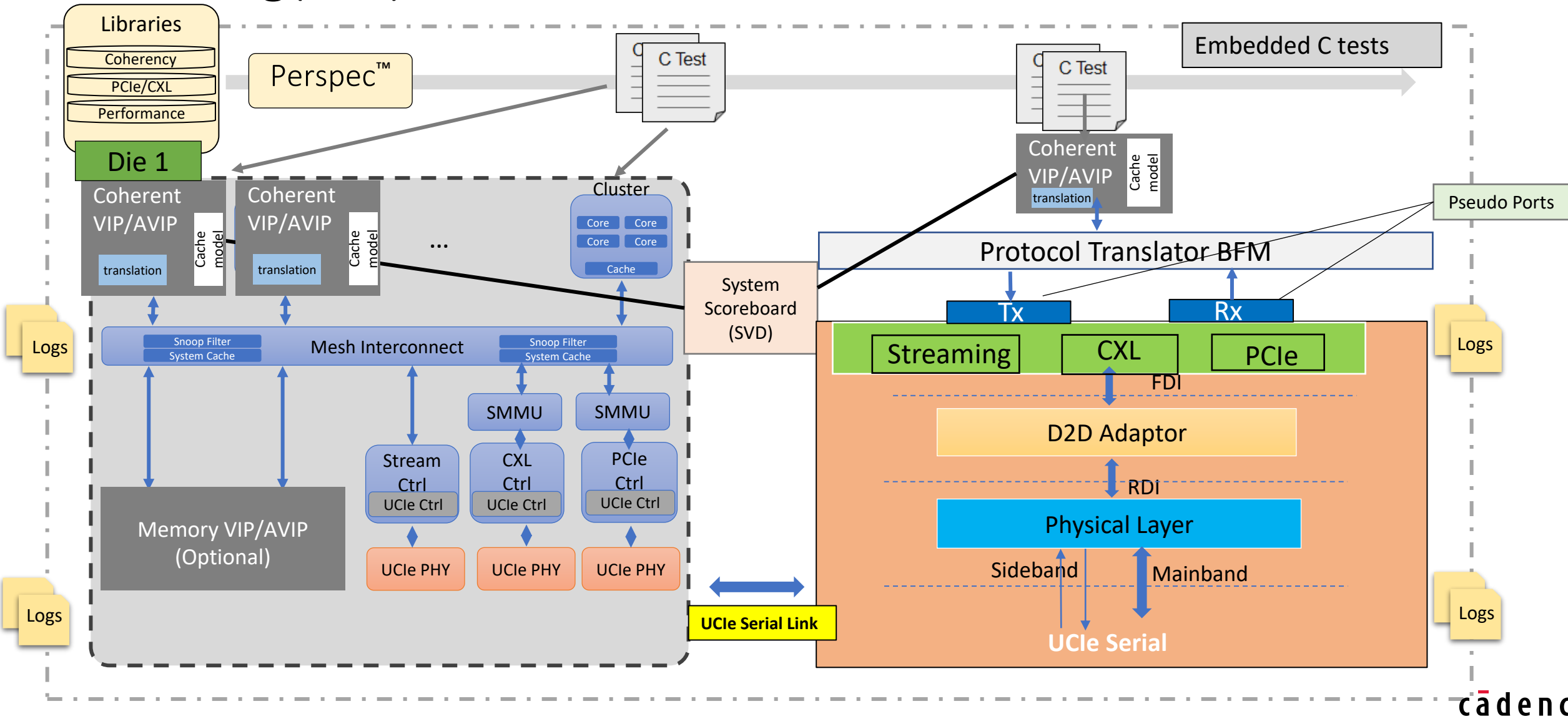
Screenshot-System Performance Analyzer(SPA)



Advantages

- Quickly understand the relationship between:
 - Bandwidth Over Time
 - Latency Over Time
 - Outstanding Transaction Over Time
- Allows bottlenecks to be identified and investigated
- Quickly identify outlier transactions with high latency and investigate the time period of occurrence

Solution- Complete System Performance & Integrity Checking(2/2)



Conclusion

- Individual Chiplet Interconnects need
 - Unit level detailed verification strategy
 - Early verification before full design availability
 - Scalable verification components to Subsystem/System level
- Multi Die System Verification needs
 - Deep Performance Analysis to identify Bottlenecks, Latency and calculate actual Bandwidth
 - Die-to-Die Scoreboards for Transaction Integrity

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